Z21. Install label in silkscreen box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22. These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Z25. Install Shunt Junper SH-J1 onto J4


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